

Day : Monday
Date: 4/19/2004
Time: 12:50:48

 **PALM INTRANET****Inventor Name Search Result**

Your Search was:

Last Name = LEE

First Name = KUN-TACK

Application#	Patent#	Status	Date Filed	Title	Inventor Name 14
<u>10728517</u>	Not Issued	030	12/05/2003	CLEANING SOLUTION AND METHOD FOR SELECTIVELY REMOVING LAYER IN A SILICIDATION PROCESS	LEE, KUN-TACK
<u>10727962</u>	Not Issued	020	12/04/2003	CLEANING SOLUTION FOR REMOVING DAMAGED PORTION OF FERROELECTRIC LAYER AND CLEANING METHOD USING THE SAME	LEE, KUN-TACK
<u>10441070</u>	Not Issued	041	05/20/2003	METHOD OF FORMING METAL INTERCONNECTION USING PLATING AND SEMICONDUCTOR DEVICE MANUFACTURED BY THE METHOD	LEE, KUN-TACK
<u>10434052</u>	Not Issued	041	05/08/2003	METHOD OF MANUFACTURING STORAGE NODES OF A SEMICONDUCTOR MEMORY DEVICE USING A TWO-STEP ETCHING PROCESS	LEE, KUN-TACK
<u>10357098</u>	Not Issued	030	02/03/2003	APPARATUS AND METHODS FOR CLEANING SEMICONDUCTOR WAFERS USING VAPORIZED CHEMICALS	LEE, KUN-TACK
<u>10135452</u>	Not Issued	061	05/01/2002	METHOD OF AND SYSTEM FOR CLEANING A SEMICONDUCTOR WAFER SIMULTANEOUSLY USING ELECTROLYTICALLY IONIZED WATER AND DILUTED HYDROFLUORIC ACID	LEE, KUN-TACK

<u>10017415</u>	Not Issued	071	12/18/2001	SINGLE TYPE OF SEMICONDUCTOR WAFER CLEANING APPARATUS AND METHOD OF USING THE SAME	LEE, KUN-TACK
<u>10012564</u>	<u>6701942</u>	150	12/12/2001	METHOD OF AND APPARATUS FOR REMOVING CONTAMINANTS FROM SURFACE OF A SUBSTRATE	LEE, KUN-TACK
<u>09945722</u>	<u>6565736</u>	150	09/05/2001	WET PROCESS FOR SEMICONDUCTOR DEVICE FABRICATION USING ANODE WATER CONTAINING OXIDATIVE SUBSTANCES AND CATHODE WATER CONTAINING REDUCTIVE SUBSTANCES, AND ANODE WATER AND CATHODE WATER USED IN THE WET PROCESS	LEE, KUN-TACK
<u>09899226</u>	<u>6712078</u>	150	07/06/2001	APPARATUS FOR CLEANING SEMICONDUCTOR WAFER AND METHOD FOR CLEANING WAFER USING THE SAME	LEE, KUN-TACK
<u>09797454</u>	Not Issued	083	03/01/2001	CLEANING SOLUTION FOR REMOVING DAMAGED PORTION OF FERROELECTRIC LAYER AND CLEANING METHOD USING THE SAME	LEE, KUN-TACK
<u>09689814</u>	Not Issued	041	10/13/2000	METHOD OF REMOVING OXIDE LAYER AND SEMICONDUCTOR MANUFACTURING APPARATUS FOR REMOVING OXIDE LAYER	LEE, KUN-TACK
<u>09662120</u>	<u>6610596</u>	150	09/14/2000	METHOD OF FORMING METAL INTERCONNECTION USING PLATING AND SEMICONDUCTOR DEVICE MANUFACTURED BY THE METHOD	LEE, KUN-TACK
<u>09451844</u>	<u>6399552</u>	150	12/01/1999	AQUEOUS CLEANING SOLUTION FOR REMOVING CONTAMINANTS SURFACE	LEE, KUN-TACK

				OF CIRCUIT SUBSTRATE CLEANING METHOD USING THE SAME
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Inventor Search Completed: No Records to Display.

**Search Another:
Inventor**

Last Name

lee

First Name

kun-tack

Search

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Search Results - Record(s) 1 through 9 of 9 returned.

☐ 1. Document ID: US 20020197944 A1

Using default format because multiple data bases are involved.

L5: Entry 1 of 9

File: PGPB

Dec 26, 2002

PGPUB-DOCUMENT-NUMBER: 20020197944

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020197944 A1

TITLE: Method and apparatus for cleaning polishing surface of polisher

PUBLICATION-DATE: December 26, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Inoue, Tatsuo	Kanagawa-ken		JP	
Komatsu, Mitsunori	Kanagawa-ken		JP	

US-CL-CURRENT: 451/444

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Drawings
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☐ 2. Document ID: US 20020108641 A1

L5: Entry 2 of 9

File: PGPB

Aug 15, 2002

PGPUB-DOCUMENT-NUMBER: 20020108641

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020108641 A1

TITLE: Single type of semiconductor wafer cleaning apparatus and method of using the same

PUBLICATION-DATE: August 15, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Lee, Kun-Tack	Suwon-city		KR	
Han, Yong-Pil	Seoul		KR	
Hah, Sang-Rok	Seoul		KR	

US-CL-CURRENT: 134/30; 134/102.1, 134/153, 134/33, 134/36, 134/902, 134/95.2,
134/95.3

ABSTRACT:

A semiconductor wafer cleaning apparatus includes a gas spraying unit, having a gas injection tube and a gas guard extending therearound, for spraying cleaning gas into a water layer formed on a wafer. The gas guard forms a small chamber just above the water layer, so that the partial pressure of gas injected from the gas injection tube is increased in the small chamber, whereupon the cleaning gas readily dissolves in the water layer. As a result, a cleaning solution having a high concentration of cleaning gas is produced, whereby the cleaning efficacy of the solution is high. Subsequently, a drying gas, such as isopropyl alcohol, for drying the wafer can be ejected onto the water layer using the gas spraying unit. Thus, the semiconductor wafer cleaning apparatus has a simple structure.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw D
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☐ 3. Document ID: US 20010021625 A1

L5: Entry 3 of 9

File: PGPB

Sep 13, 2001

PGPUB-DOCUMENT-NUMBER: 20010021625

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20010021625 A1

TITLE: Method and apparatus for cleaning polishing surface of polisher

PUBLICATION-DATE: September 13, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Inoue, Tatsuo	Kanagawa-ken		JP	
Komatsu, Mitsunori	Kanagawa-ken		JP	

US-CL-CURRENT: 451/56

ABSTRACT:

A polishing surface cleaning method and apparatus are capable of effectively removing the polishing residue from the polishing surface of a polishing table in a polisher by using a minimal amount of cleaning liquid. In the polisher, a workpiece to be polished is pressed against the polishing surface of the polishing table to polish the workpiece by relative motion between the polishing surface and the workpiece. The polishing surface cleaning apparatus uses mixing spray nozzles for mixing together a cleaning liquid and a gas and spraying the resulting fluid mixture on the polishing surface to clean it.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw D
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☐ 4. Document ID: US 6610168 B1

L5: Entry 4 of 9

File: USPT

Aug 26, 2003

US-PAT-NO: 6610168

DOCUMENT-IDENTIFIER: US 6610168 B1

**** See image for Certificate of Correction ****

TITLE: Resist film removal apparatus and resist film removal method

DATE-ISSUED: August 26, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Miki; Nobuhiro	Tokyo			JP
Nitta; Takahisa	Tokyo			JP

US-CL-CURRENT: 156/344; 134/26, 134/30, 134/39, 430/256, 430/260

ABSTRACT:

A line slit nozzle for spraying steam is disposed along a diameter of a resist film. Steam containing a mist is sprayed onto a surface of the resist film. The film is thereby peeled off and removed. By using a change in physical properties (swelling, etc.) of the resist film by water, the film is easily and surely peeled off. Breakaway from much resources/energy consumption type techniques is realized. In other words, realized are environment-symbiosis type techniques by which resist films can be removed independently of the quantity of energy and kinds of chemical solvents.

3 Claims, 10 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 7

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw De
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☐ 5. Document ID: US 6598805 B2

L5: Entry 5 of 9

File: USPT

Jul 29, 2003

US-PAT-NO: 6598805

DOCUMENT-IDENTIFIER: US 6598805 B2

TITLE: Substrate cleaning apparatus

DATE-ISSUED: July 29, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Sakai; Takamasa	Kyoto			JP
Hirae; Sadao	Kyoto			JP

h e b b g e e e f e ef b e

US-CL-CURRENT: 239/128; 134/22.15, 134/30, 134/36, 134/902, 239/132, 239/136,
239/137, 239/139, 239/419

ABSTRACT:

A gas mixture of dry steam and nitrogen gas serving as carrier gas is blown into a hot water mist injection port for rendering the nitrogen gas serve as a medium absorbing latent heat of condensation, thereby smoothly progressing condensation of water vapor and efficiently forming hot water mist. The water vapor is condensed in the hot water mist injection port formed by a cylindrical pipe for supplying latent heat of condensation to the nitrogen gas and dilating the same, thereby accelerating the flow of the hot water mist and spraying the hot water mist to a substrate from the hot water mist injection port at a high speed. Small droplets contained in the high-speed hot water mist have high kinetic energy and high thermal energy, for exhibiting a large colliding effect and a high activation effect with respect to small contaminants adhering to the substrate. A substrate cleaning apparatus capable of spraying hot water mist attaining a high cleaning effect to a substrate is provided.

11 Claims, 3 Drawing figures
 Exemplary Claim Number: 1
 Number of Drawing Sheets: 3

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw De
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☐ 6. Document ID: US 6443816 B2

L5: Entry 6 of 9

File: USPT

Sep 3, 2002

US-PAT-NO: 6443816
 DOCUMENT-IDENTIFIER: US 6443816 B2

TITLE: Method and apparatus for cleaning polishing surface of polisher

DATE-ISSUED: September 3, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Inoue; Tatsuo	kanagawa-ken			JP
Komatsu; Mitsunori	kanagawa-ken			JP

US-CL-CURRENT: 451/56; 451/444, 451/72

ABSTRACT:

A polishing surface cleaning method and apparatus are capable of effectively removing the polishing residue from the polishing surface of a polishing table in a polisher by using a minimal amount of cleaning liquid. In the polisher, a workpiece to be polished is pressed against the polishing surface of the polishing table to polish the workpiece by relative motion between the polishing surface and the workpiece. The polishing surface cleaning apparatus uses mixing spray nozzles for mixing together a cleaning liquid and a gas and spraying the resulting fluid mixture on the polishing surface to clean it.

9 Claims, 10 Drawing figures
Exemplary Claim Number: 1
Number of Drawing Sheets: 5

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw. De
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☐ 7. Document ID: US 5012980 A

L5: Entry 7 of 9

File: USPT

May 7, 1991

US-PAT-NO: 5012980
DOCUMENT-IDENTIFIER: US 5012980 A

TITLE: Linear-spraying device

DATE-ISSUED: May 7, 1991

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Viannay; Stephane G. J.	Voisin-le-Bretonneux			FR
Roth; Bernard M.	Boulogne-Billancourt			FR
Mirigay; Solange M. V.	Chaville			FR
Chastang; Georges J. B.	Coignieres			FR

US-CL-CURRENT: 239/423; 239/543, 239/568

ABSTRACT:

The pressurized gas is supplied by two sleeves separated by a sprayer device forming a funnel. The narrow end of the funnel has a spraying head with, in the plane of symmetry (P) of the device, at least one slot through which the liquid flows. The pressurized gas passes through a series of openings provided on either side of the slot. A liquid supply tube is arranged parallel in relation to the wide end of the funnel and has openings through which the liquid flows directly or indirectly into the funnel and passes through the slot without any appreciable pressure.

9 Claims, 6 Drawing figures
Exemplary Claim Number: 1
Number of Drawing Sheets: 3

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw. De
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☐ 8. Document ID: US 4799941 A

L5: Entry 8 of 9

File: USPT

Jan 24, 1989

US-PAT-NO: 4799941
DOCUMENT-IDENTIFIER: US 4799941 A

TITLE: Method and arrangement for condensing flue gases

DATE-ISSUED: January 24, 1989

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Westermarck; Mats O. J.	Taby			SE

US-CL-CURRENT: 95/199; 110/215, 122/7R, 261/146, 261/151, 261/153, 261/157,
261/DIG.9, 95/225, 96/266

ABSTRACT:

The invention relates to a method for condensing flue gas in combustion plants, and an arrangement of apparatus herefor. In accordance with the invention the flue gas is cooled and humidified by bringing the gas into direct contact with water, whereafter the water vapor in the gas is cooled and condensed, the heat of condensation being recovered by indirect heat exchange. The heat of condensation is transferred partially to a heat absorbing medium, preferably return water in a district heating network, and partially to a circuit in which water is circulated within the plant, this water being used for heating and humidifying the combustion air.

10 Claims, 2 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 1

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw De
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☐ 9. Document ID: US 2204771 A

L5: Entry 9 of 9

File: USOC

Jun 18, 1940

US-PAT-NO: 2204771

DOCUMENT-IDENTIFIER: US 2204771 A

TITLE: Gas washing means

DATE-ISSUED: June 18, 1940

INVENTOR-NAME: RICE OWEN R; SCHOFIELD WILFRED C

US-CL-CURRENT: 261/22, 261/111

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw De
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Term	Documents
GAS	2466758

GASES	602437
SPRAYING	310917
SPRAYINGS	566
(3 AND (GAS ADJ SPRAYING)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	9
(L3 AND (GAS SPRAYING)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	9

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